IN THE SPECIFICATION

In accordance with 37 CFR 1.121(b)(1)(iii), Attachment B contains marked up versions of the replacement paragraphs illustrating the newly introduced changes in the specification.

Please replace the paragraph on page 3, starting on line 8, with the following replacement paragraph.

A third object of the present invention is to provide an electric contact probe assembly which demonstrates low electric resistance.

Please replace the paragraph on page 3, starting on line 12, with the following replacement paragraph.

According to the present invention such objects can be accomplished by providing an electric contact probe assembly, comprising: a non-electroconductive support sheet having a front and reverse sides and at least one through hole; an electroconductive patch attached to a part of the support sheet adjacent to the through hole; an electroconductive resilient probe member having a base end attached to the patch and a free end projecting from the front side of the support sheet; and a circuit board placed over the reverse side of the support sheet and having a circuit layer incorporated therein and a terminal facing the reverse side of the support sheet; the support sheet being fixedly attached to the circuit board by an electroconductive bonding member which both physically and electrically connects the patch with the terminal.

Please replace the paragraph starting on page 10, line 21, with the following replacement paragraph.

A burn-in test can be conducted in this manner. Electric current flows axially through the coil-shaped resilient probe member 2 as far as the closely wound electrode section 2b and

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the closely wound conical section or the electrode section 2c are concerned, and circumferentially through the coil-shaped resilient probe member 2 only in the coarsely wound section 2a (which consists of a single turn in the case of the illustrated embodiment). Therefore, the electric flow path is extremely short, and this contributes to the reduction in the resistance and inductance against the transmission of high frequency signals. The connection to the relay circuit board 6 is achieved by soldering, instead of a simple contact by an electrode (as is the case with an electric contact probe assembly having two moveable ends), so that the problem of a contact resistance does not exist. By minimizing the thickness of the support sheet 3, the thickness of the electric contact probe assembly 1 (the axial length of the coil-shaped resilient probe member 2) can be minimized, and so is the overall thickness of the electric contact probe assembly.

Please replace the paragraph starting on page 10, line 11, with the following replacement paragraph.

When the electrode section 2b of the coil-shaped resilient probe member 2 is desired to be brought into contact with the object to be contacted in the axial direction, the electrode section 2b should have a perpendicularity as precisely as possible. Therefore, the coil end of the closely wound section 2c of the coil-shaped resilient probe member 2 may be ground so as to form a ground surface 2d which is perpendicular to the axial line of the coil-shaped resilient probe member 2 (the center line in the drawing) as shown in Figure 5. This facilitates the placement of the coil-shaped resilient probe member 2 on the support sheet 3. In the case of the embodiment shown in Figure 5, both ends of the coil are ground. Therefore, the coil end of the electrode section 2b is also formed with a ground surface 2e which is perpendicular to the coil axial line. As a result, the electrode section 2b can be brought into contact with the planar pad 9a such as the one as illustrated in Figure 4 in a stable fashion. In particular,

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because the contact surface with respect to the pad 9a is relatively large, a localized high contact pressure can be avoided, and the pad 9a would not be damaged even when it is made of a relatively soft material.

Please replace the paragraph on page 16, starting on line 2, with the following replacement paragraph.

The closely wound section 2c can be integrally attached to the support sheet 3 with the coil end of the closely wound section 2c fitted into the inner bore jointly defined by the raised pieces, and located so as to reach the reverse surface of the base portion of the patch 13. By doing so, the projection of the coil-shaped resilient probe member 2 can be reduced even further (by the combined thickness of the support sheet 3 and the patch 13), and so is the thickness of the entire assembly.

Please replace the paragraph on page 16, starting on line 16, with the following replacement paragraph.

The object to be contacted is not limited to those having a planar surface as was the case with the pad 9a which was illustrated earlier, but may have a bulging surface as shown on the solder ball 14 in Figure 20. This coil-shaped resilient probe member 15 comprises an intermediate coarsely wound section 15a, a closely wound section 15c on a coil end which is soldered to the patch 4, and an electrode section 15b which consists of a coarsely wound section connected to the afore-mentioned coarsely wound section 15a.

Please replace the paragraph on page 17, starting on line 5, with the following replacement paragraph.

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In this straight coil-shaped resilient probe member 15 also, as was the case with the embodiments illustrated in Figure 7, both ends may be ground, only one of the ends may be ground or a reduced diameter section (planar end) may be provided on the base end, and these embodiments produce similar results as the corresponding embodiments shown in Figures 5 to 7.

Please replace the paragraph on page 18, starting on line 8, with the following replacement paragraph.

Thus, the present invention provides favorable handling even when a large number of resilient probe members are provided on a single support sheet. Because through holes can be easily formed in such a support sheet, by fixedly attaching an electroconductive member to the support sheet with a part of the electroconductive member exposed to the through hole, the support sheet can be bonded to the terminal of the circuit board by virtue of the solder or brazing material which is filled into the through hole. Because there is no intervening contact member in the path of electric conduction, the high frequency performance can be improved, and a satisfactory testing of semiconductor devices for high frequency signals is made possible.

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